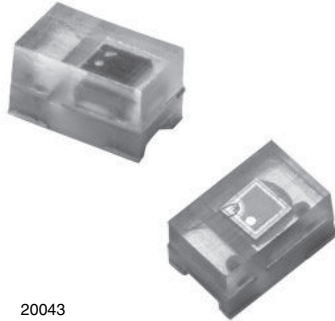




Silicon Phototransistor in 0805 Package



20043

DESCRIPTION

TEMT7000X01 is a high speed silicon NPN epitaxial planar phototransistor in a miniature 0805 package for surface mounting on printed boards. The device is sensitive to visible and near infrared radiation.

FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\phi = \pm 60^\circ$
- Package matched with IR emitter series VSMB1940X01
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



Note

** Please see document "Vishay Material Category Policy": www.vishay.com/doc?99902

APPLICATIONS

- Detector in automotive applications
- Light sensors
- Radiation sensors

PRODUCT SUMMARY			
COMPONENT	I _{caE} (μA)	φ (deg)	λ _{0.1} (nm)
TEMT7000X01	225 to 675	± 60	470 to 1090

Note

- Test condition see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TEMT7000X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Collector emitter voltage		V _{CEO}	20	V
Emitter collector voltage		V _{ECO}	7	V
Collector current		I _C	20	mA
Power power dissipation	T _{amb} ≤ 55 °C	P _V	100	mW
Junction temperature		T _J	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow profile fig. 8	T _{sd}	260	°C
Thermal resistance junction/ambient	Acc. J-STD-051	R _{thJA}	270	K/W

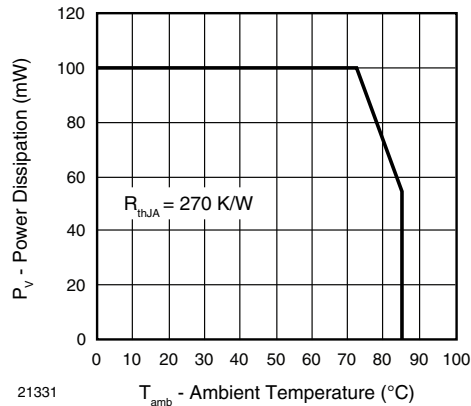


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Collector emitter breakdown voltage	$I_C = 0.1\text{ mA}$	V_{CEO}	20			V
Collector dark current	$V_{CE} = 5\text{ V}, E = 0$	I_{CEO}		1	100	nA
Collector emitter capacitance	$V_{CE} = 0\text{ V}, f = 1\text{ MHz}, E = 0$	C_{CEO}		25		pF
Collector light current	$E_e = 1\text{ mW/cm}^2, \lambda = 950\text{ nm}, V_{CE} = 5\text{ V}$	I_{CA}	225	450	675	μA
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ_p		850		nm
Range of spectral bandwidth		$\lambda_{0.1}$		470 to 1090		nm
Collector emitter saturation voltage	$I_C = 0.05\text{ mA}$	V_{CEsat}			0.4	V
Temperature coefficient of I_{ca}	$E_e = 1\text{ mW/cm}^2, \lambda = 950\text{ nm}, V_{CE} = 5\text{ V}$	Tk_{Ica}		1.1		%/K

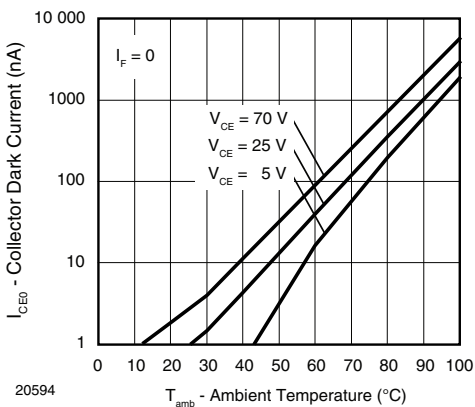
BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)


Fig. 2 - Collector Dark Current vs. Ambient Temperature

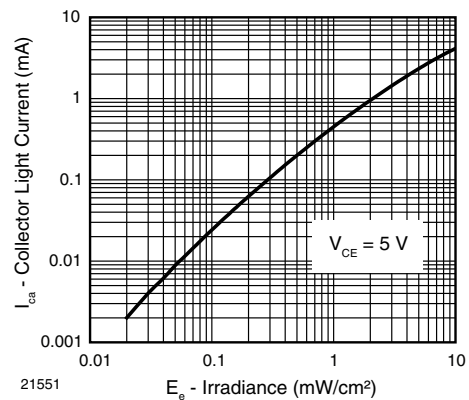


Fig. 3 - Collector Light Current vs. Irradiance

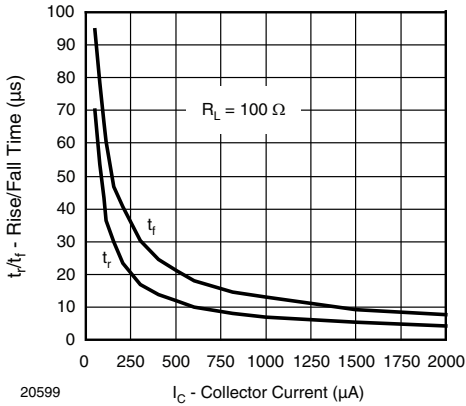


Fig. 4 - Rise/Fall Time vs. Collector Current

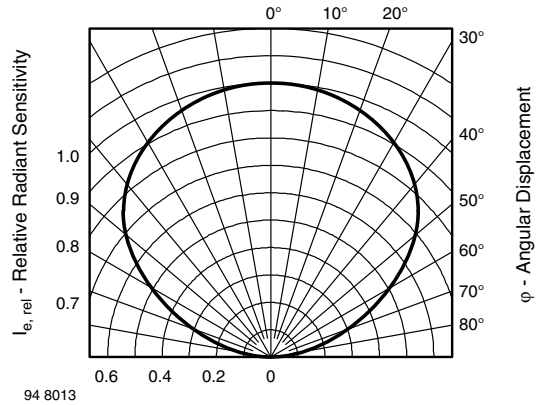


Fig. 6 - Relative Radiant Sensitivity vs. Angular Displacement

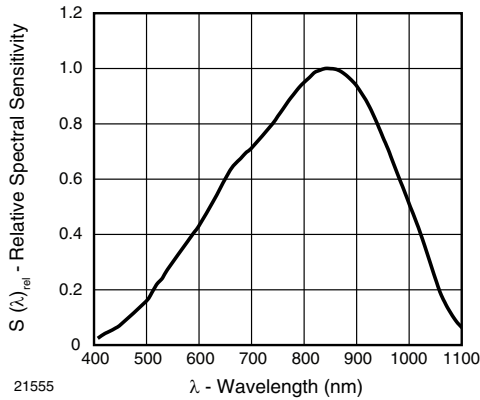


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

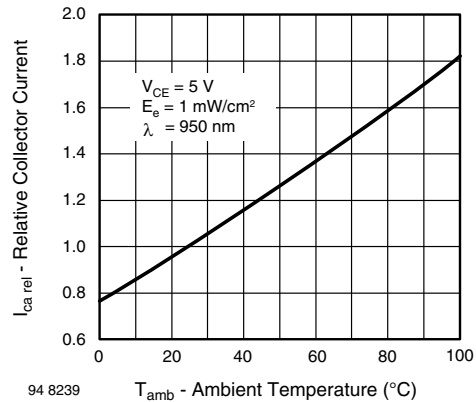


Fig. 7 - Relative Collector Current vs. Ambient Temperature

REFLOW SOLDER PROFILE

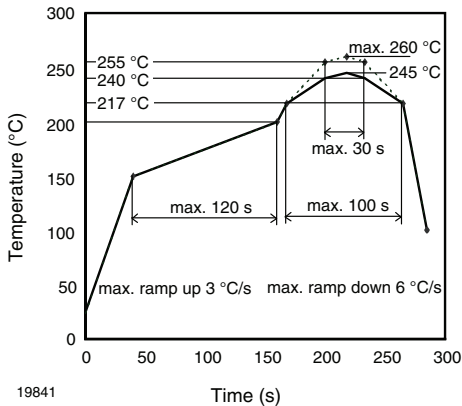


Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

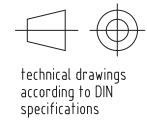
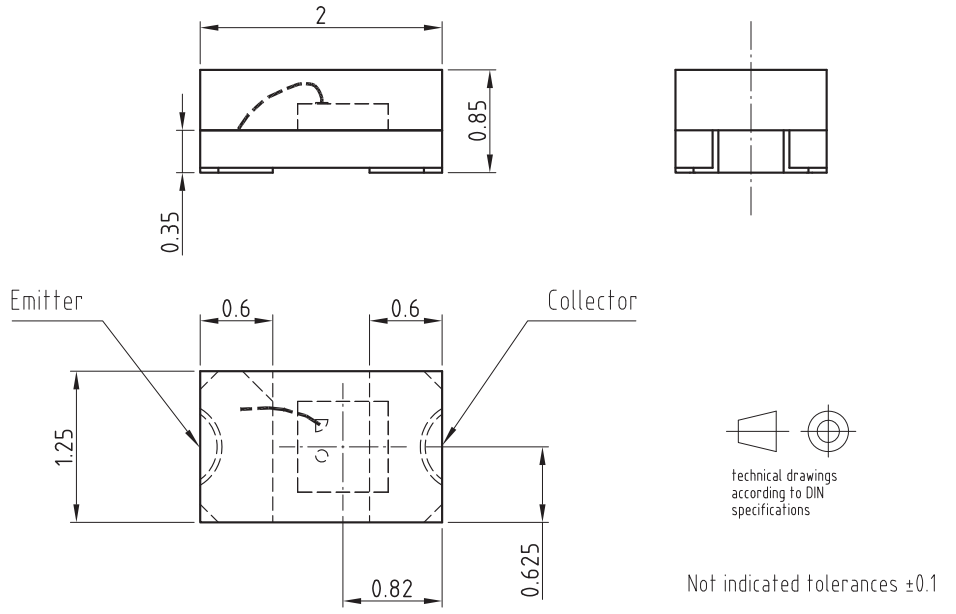
Moisture sensitivity level 3, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), $RH < 5\%$.

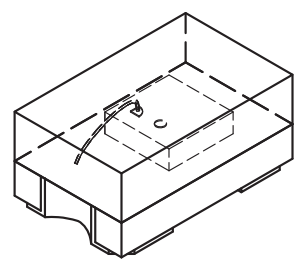


PACKAGE DIMENSIONS in millimeters

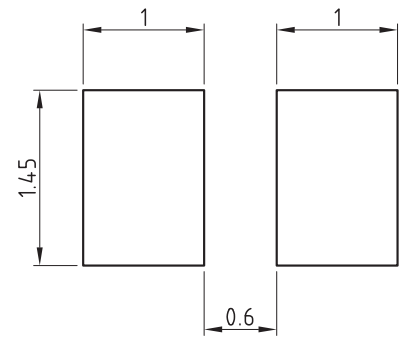


technical drawings according to DIN specifications

Not indicated tolerances ±0.1



Recommended solder pad Footprint



Drawing-No.: 6.541-5063.01-4
Issue: 3; 23.02.07
19757



BLISTER TAPE DIMENSIONS in millimeters



Drawing-No.: 9.700-5310.01-4
 Issue: 2; 14.08.07
 20690

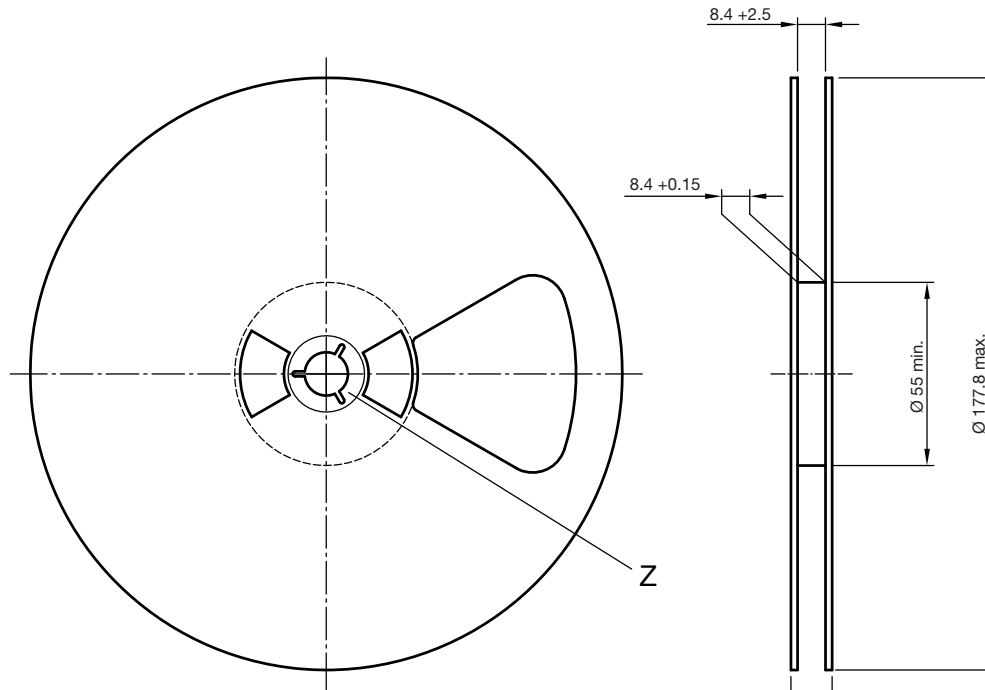
Not indicated tolerances ±0.1

Quantity per reel: 3000 pcs

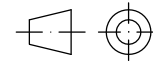
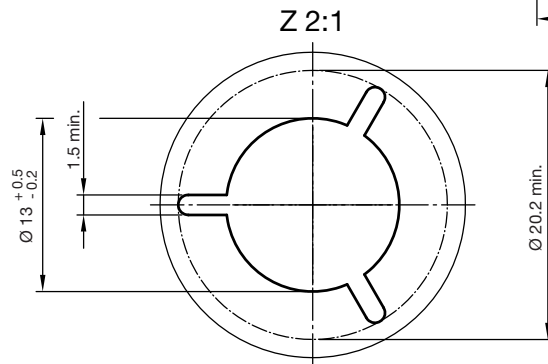
technical drawings according to DIN specifications



REEL DIMENSIONS in millimeters



Form of the leave open of the wheel is supplier specific.



technical drawings according to DIN specifications

Drawing-No.: 9.800-5096.01-4
Issue: 2; 26.04.10
20875



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.